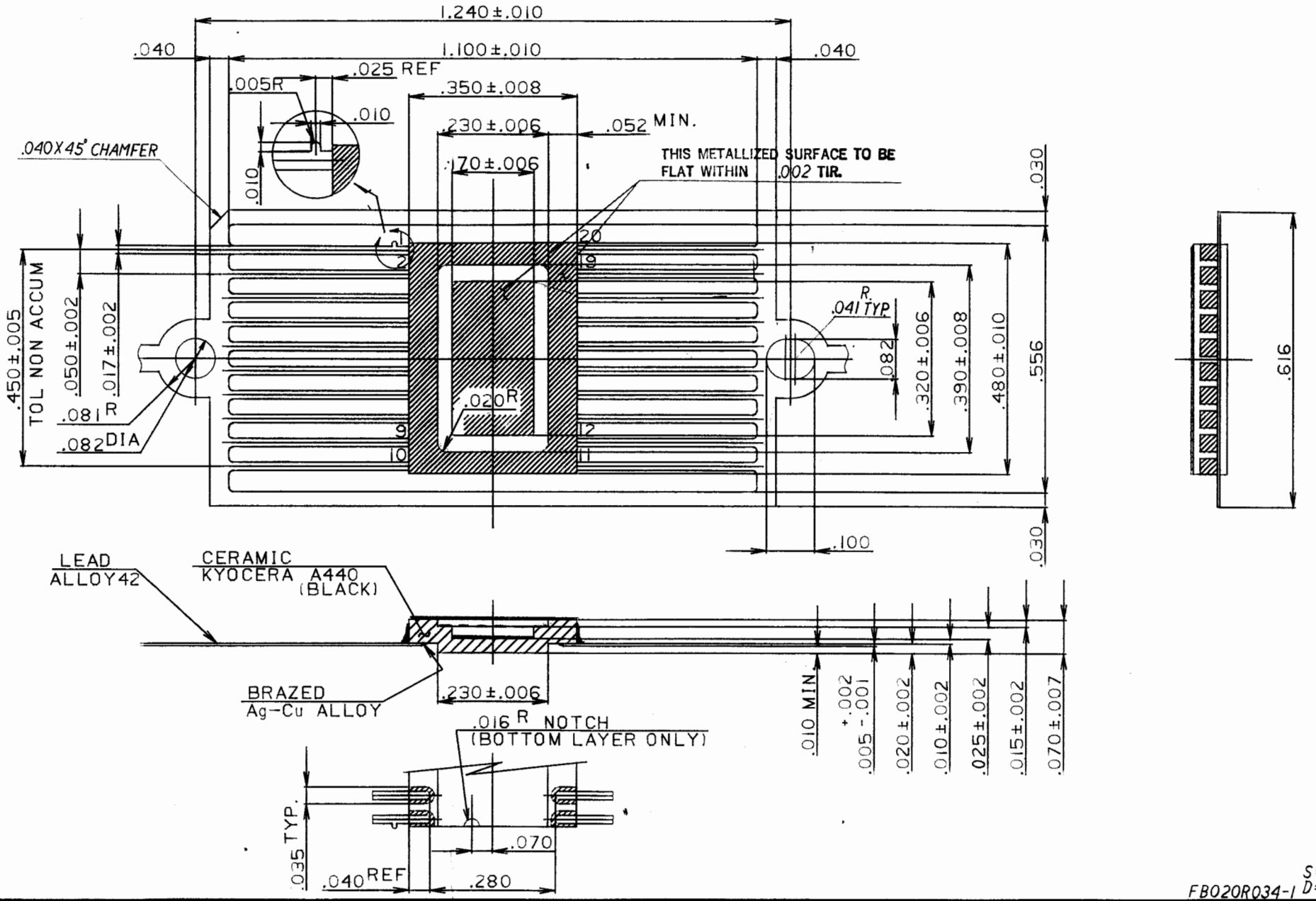


S=0
D=0

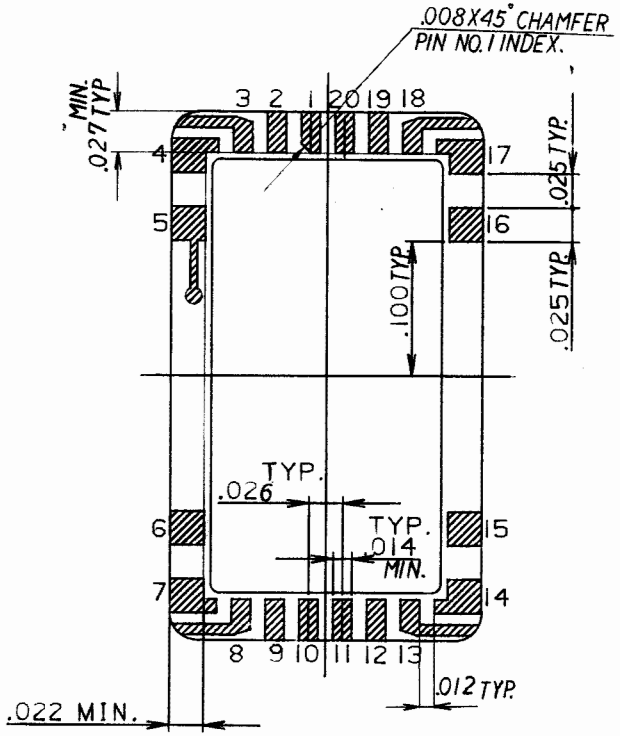
FB020R034-1

MODIFICATIONS					
CHANGE	DATE	DRAWN	CHECKED	APPROVED	

NAME	20 LEAD FLAT PACKAGE	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED
SCALE	MATERIAL	±1.0% N.L.T.±.005	T. Higashigata	Tatsuchi
5 : 1	AS INDICATED		APPROVED	DATE
				JAN.24'85

KYOCERA CORPORATION KYOTO JAPAN

DWG.NO. KD-85034 1/2



BONDING PATTERN

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION
2. LEAD RESISTANCE : 0.3 Ω MAX.
3. SEAL AREA TO BE METALLIZED
4. DIE ATTACH AREA TO BE METALLIZED
5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

MODIFICATIONS					
CHANGE	INIT.	DRAWN	CHECKED	APPROVED	

NAME: 20 LEAD FLAT PACKAGE		TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN: Higashigata / CHECKED: T.Atsuchi
SCALE: 10 : 1	MATERIAL: —		APPROVED: / DATE: JAN.24.'85
KYOCERA CORPORATION KYOTO JAPAN		DWG.NO. KD-85034	2/2